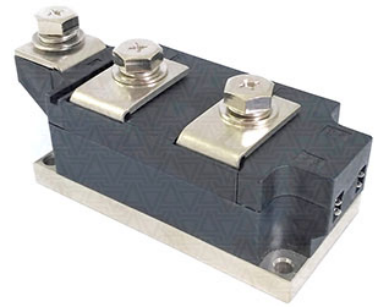


# Модуль диодный МДД-500-26



Средний прямой ток	$I_{FAV}$					500 A				
Повторяющееся импульсное обратное напряжение	$U_{RRM}$					800 - 2600 В				
$U_{RRM}$ , В	800	1000	1200	1400	1600	1800	2000	2200	2400	2600
Класс по напряжению	8	10	12	14	16	18	20	22	24	26
$T_j$ , °C	-60 ÷ 150									

SYMBOL	CHARACTERISTIC	TEST CONDITIONS	$T_j$ (°C)	VALUE			UNIT	
				Min	Type	Max		
$I_{F(AV)}$	Mean forward current	180° half sine wave 50Hz Single side cooled, $T_c=100^\circ\text{C}$	150			500	A	
$I_{F(RMS)}$	RMS forward current		150			785	A	
$I_{RRM}$	Repetitive peak current	at $V_{RRM}$	150			40	mA	
$I_{FSM}$	Surge forward current	10ms half sine wave	150			16.0	KA	
$I^2t$	$I^2T$ for fusing coordination	$V_R=0.6V_{RRM}$				1280	$\text{A}^2\text{s}\cdot 10^3$	
$V_{FO}$	Threshold voltage		150			0.75	V	
$r_F$	Forward slop resistance					0.30	mΩ	
$V_{FM}$	Peak forward voltage	$I_{FM}=1800\text{A}$	25			1.45	V	
$R_{th(j-c)}$	Thermal resistance Junction to case	At 180°sine' Single side cooled per chip				0.090	°C /W	
$R_{th(c-h)}$	Thermal resistance case to heatsink	At 180°sine' Single side cooled per chip				0.024	°C /W	
$V_{iso}$	Isolation voltage	50Hz,R.M.S,t=1min, $I_{iso}:1\text{mA}(\text{max})$		3000			V	
$F_m$	Terminal connection torque(M10)				12.0		N·m	
	Mounting torque(M6)				6.0		N·m	
$T_{stg}$	Stored temperature			-40		125	°C	
$W_t$	Weight				1430		g	
Outline	MTD5							

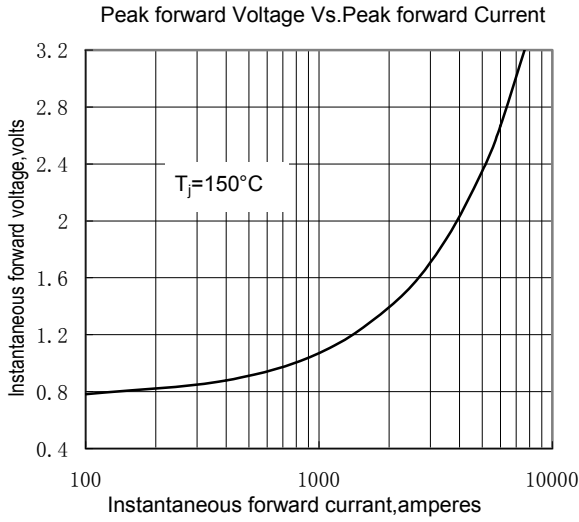


Fig.1

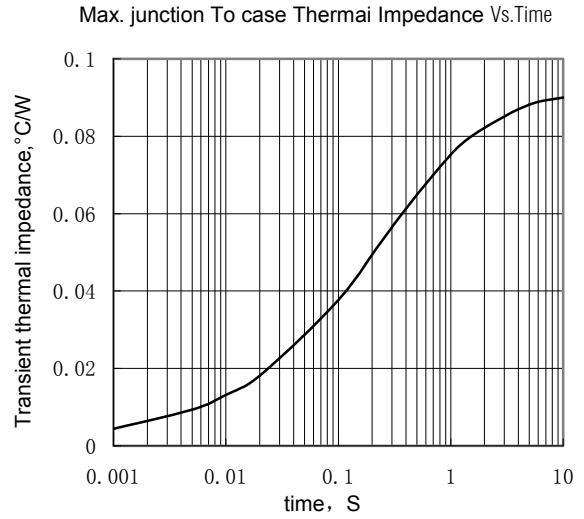


Fig.2

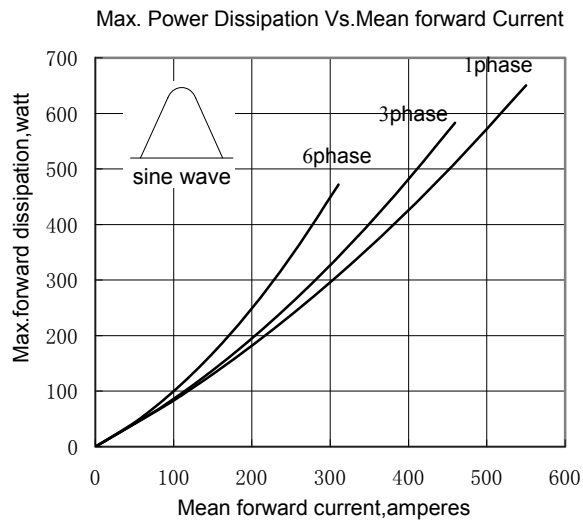


Fig.3

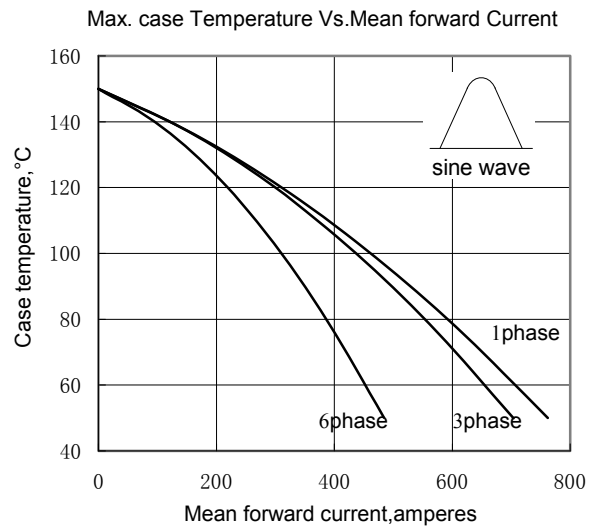


Fig.4

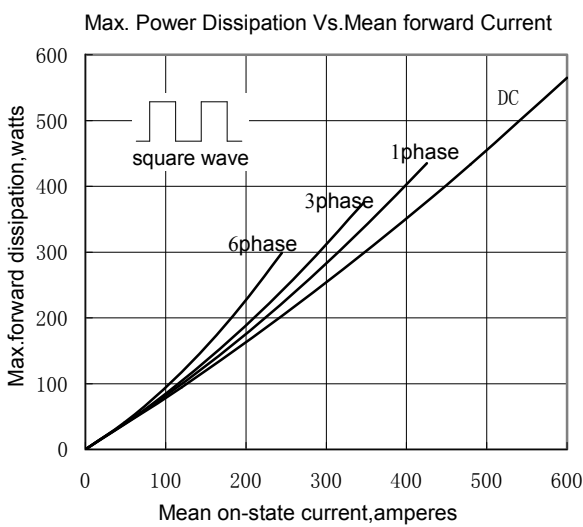


Fig.5

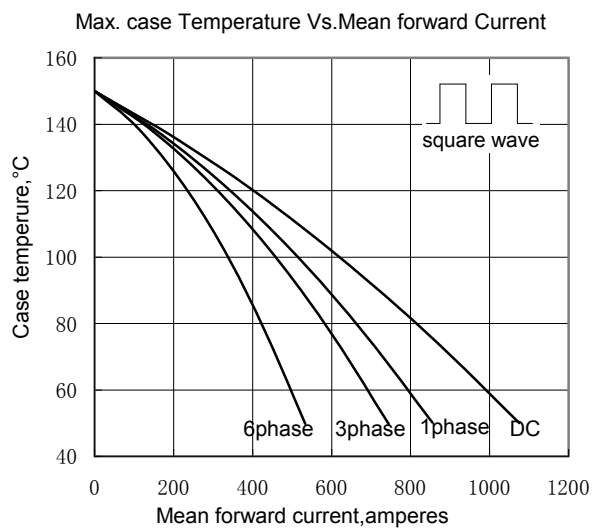


Fig.6

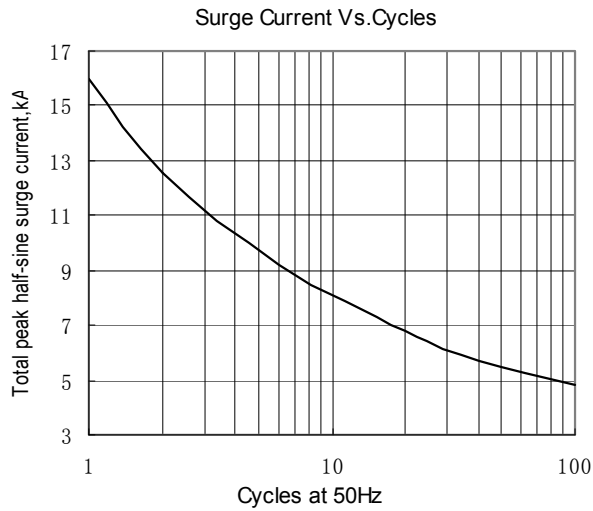


Fig.7

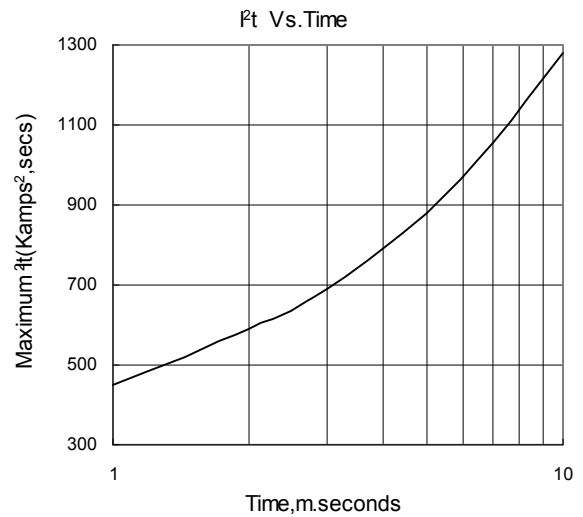
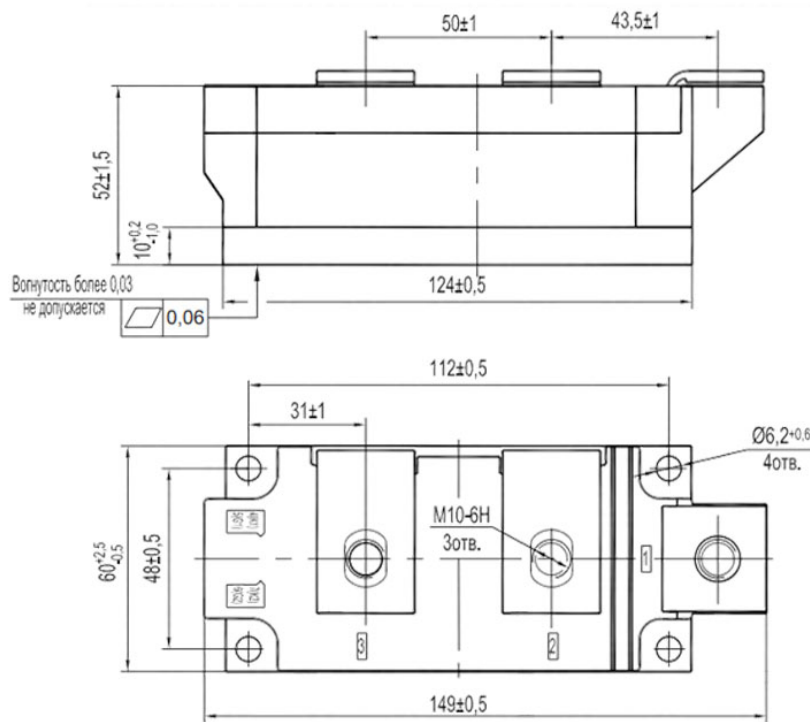


Fig.8

**ГАБАРИТНЫЕ РАЗМЕРЫ**

Тип корпуса: MDT5



Все размеры в миллиметрах



3 – Анод/Катод, 2 – Катод, 1 – Анод